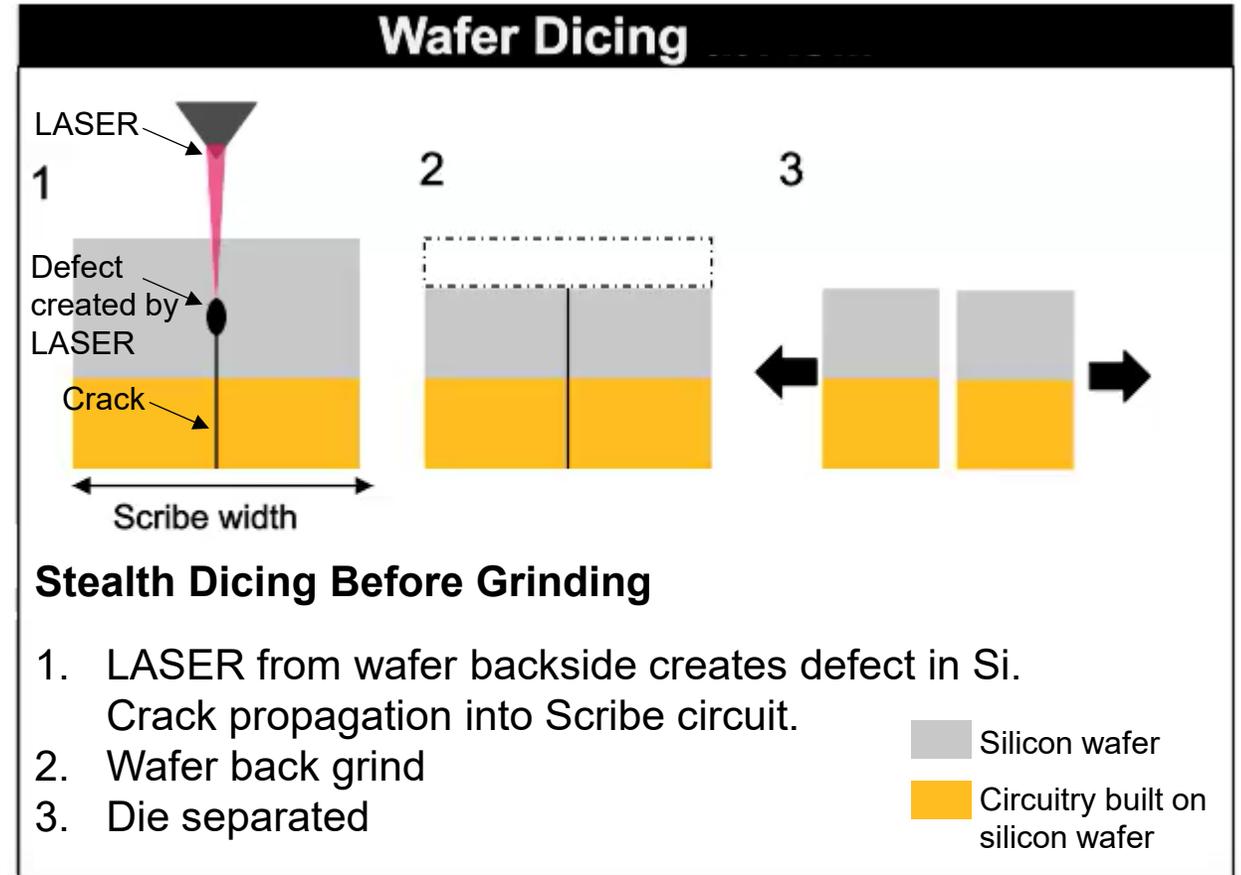


Making Memory Chips Addendum

Reviewed 2026

Addendum

- This addendum applies to:
 - “Making memory chips” video, minute 2:16
 - “Journey of a memory chip” video, minute 2:20
- In these videos it is conveyed that in Assembly, wafers are first thinned, attached to an adhesive backing and then diced into individual die using a diamond edge saw.
- Since the videos were created, industry has shifted to **Stealth Dicing Before Grinding (SDBG)** as depicted in the schematic.
- SDBG is a laser-based dicing process that produces a modified layer (dislocation defect) within the silicon before wafer thinning (back grind). The process is preferred for ultra-thin, high-density chips where dicing quality is critical.



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